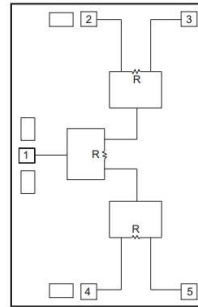


Performance

- Frequency: 2.5~6.0GHz
- Insertion loss: 1.5dB
- Chip size: 2.00*1.25*0.1mm

Function Diagram

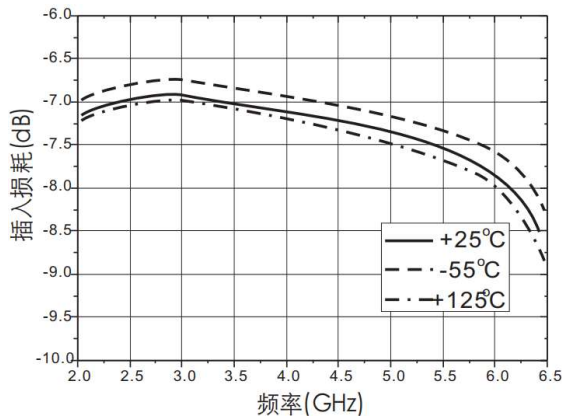


Electrical Specifications (Ta=+25°C, 50Ω system)

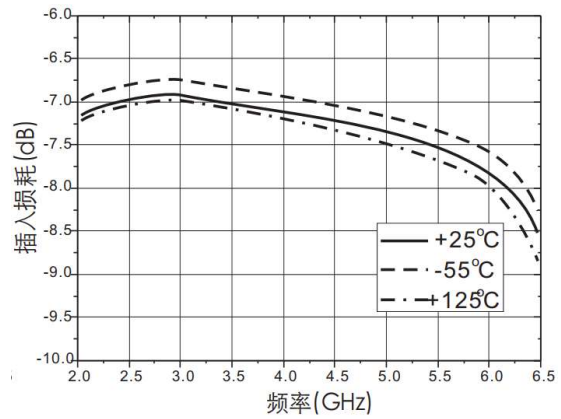
Parameter	Min	Typical	Max	Unit
Frequency Range	2.5~6.0			GHz
Insertion Loss	-	1.5	2.0	dB
Insertion Loss Ripple	-	±0.5	-	dB
Isolation	17	20	-	dB
Input Return Loss	20	25	-	dB
Output Return Loss	17	20	-	dB

Test Curves

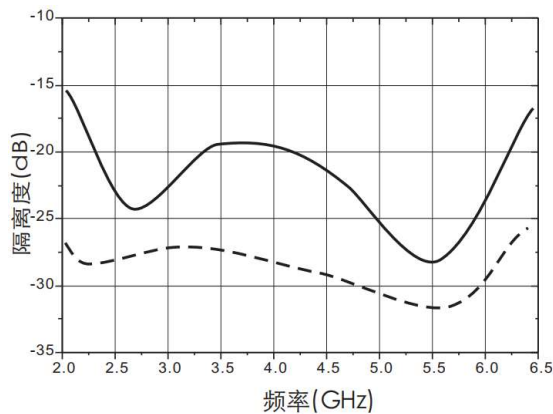
2/4 Port Insertion loss vs. Freq



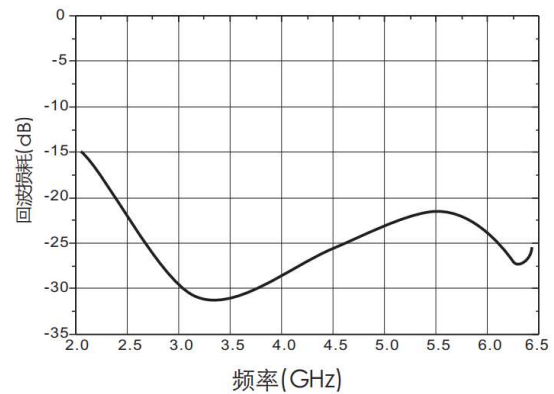
3/5 Port Insertion loss vs. Freq

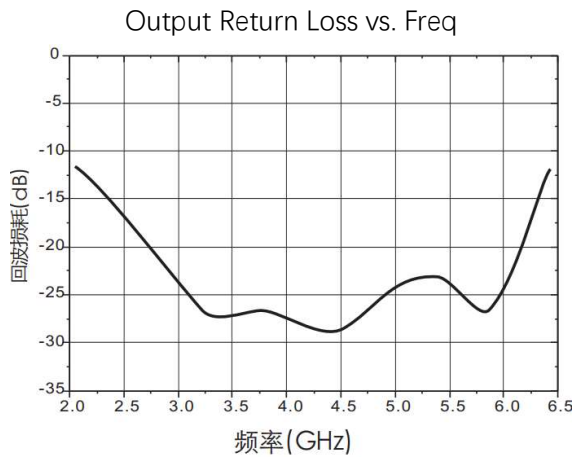


Isolation vs. Freq



Input Return Loss vs. Freq





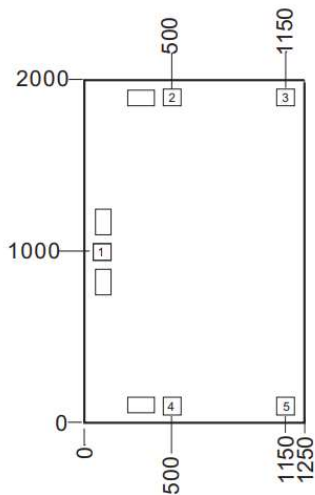
Absolute Max Ratings

Parameter	Value
Input Signal Power	+31dBm
Storage Temperature	-65~150°C
Operating Temperature	-55~125°C
Junction Temperature	175°C
Static protection Grade (HBM)	Class 1A



ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS

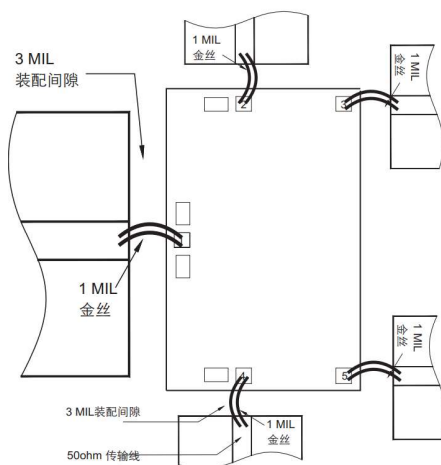
Outline Size



Note:

1. Unit: um
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated
Pads size: 100*100 um
5. Don't bonding on thru holds
6. Tolerance: $\pm 50\mu\text{m}$

Assembly Diagram



Bonding Definition

No.	Symbol	Description
1	IN	RF input, 50ohm
2,3,4,5	Out1,Out2, Out3,Out4	RF Output, 50ohm
-	GND	Bottom must be grounded